

# 408 II Series

**TAPER AND DETAPER**



**microcontrol  
electronic**

Milan - ITALY

[www.microcontrol.org](http://www.microcontrol.org)

# 408 II Series

## TAPER AND DETAPER

Taping Station

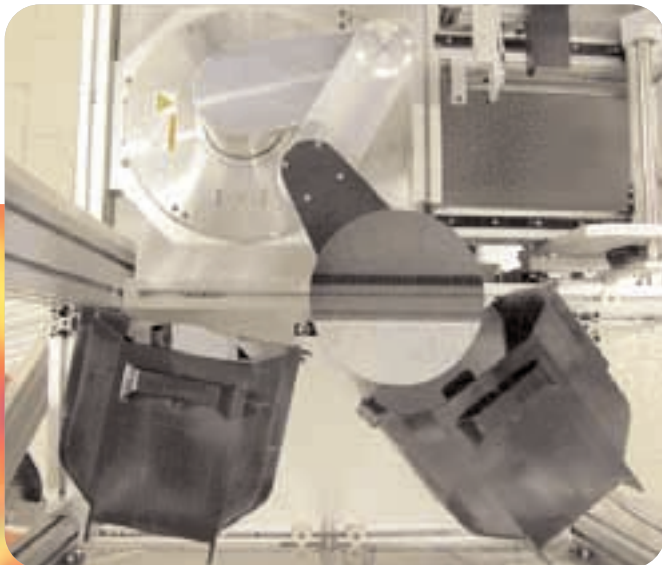


TAPER

Ultra thin wafers processing:  
our special zero force lamination  
technology eliminates extra bow  
due to tape tension on wafers

Our unique taping roller allows to perfectly  
process very high bumped wafers

Loading Station



### Microcontrol Electronic history

Established in 1976, Microcontrol Electronic introduced the **first worldwide automatic Taper and Detaper** on the market in 1984.

Since then hundreds of equipment has been sold all over the world to the most important Companies such as Atmel, Ibm, Infineon, Intel, Micron, Motorola, Philips, Stm and TI. Microcontrol Electronic Taper and Detaper can be customized according to customers' process specification: applications with special tapes like photosensitive Dupont Riston® and thermal sensible Rexpan® have been already successfully experienced.

### Lowest cost of ownership through "total gap control"

software fully adjustable gap between wafers

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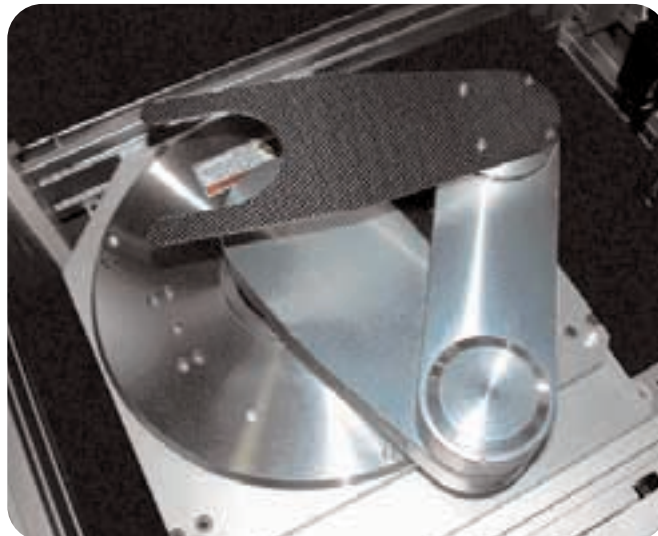
lowest tape consumption

### HIGHEST THROUGHPUT

TAPER 100 wafers/hour

DETAPER 110 wafers/hour

Adept Robot with Carbon Fiber Handler



UV Station



Ultra thin wafer detaping  
with our special chuck

Fully adjustable software and  
mechanical detaping process

Detaping Station



DETAPER

# 408 II Series

## TAPER

### SYSTEM SPECIFICATIONS

WAFER SIZE	Up to 8"
THROUGHPUT	<b>100 wfrs/hr</b>
CENTERING / ALIGNMENT	CONTACTLESS VISION SYSTEM
TAPE COMPATIBILITY	ALL KIND OF TAPES
MINIMUM TAPE WIDTH	6" <b>165mm</b> 8" <b>215mm</b>
N° of 8" WAFERS WITH 100m ROLL	<b>470 Wfrs</b>
FOOT PRINT	<b>1m<sup>2</sup></b>
CE marking	Full compliance
SEMI Standard	Full compliance
SECS-GEM full compliance	Option
WAFER ID / CASSETTE ID	Option OCR - DOT matrix - BCR
SMIF SYSTEM	Option
M.T.B.F.	550 hrs
M.T.T.R.	1hr

The above systems specification are process dependant.

# 408 II Series

## DETAPER

### SYSTEM SPECIFICATIONS

WAFER SIZE	Up to 8"
THROUGHPUT	<b>110 wfrs/hr</b>
CENTERING / ALIGNMENT	CONTACTLESS VISION SYSTEM
TAPE COMPATIBILITY	ALL KIND OF TAPES
FOOT PRINT	<b>1m<sup>2</sup></b>
CE marking	Full compliance
SEMI Standard	Full compliance
SECS-GEM full compliance	Option
WAFER ID / CASSETTE ID	Option OCR - DOT matrix - BCR
UV Station	Option
SMIF SYSTEM	Option
M.T.B.F.	550 hrs
M.T.T.R.	1hr

The above systems specification are process dependant.



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9160 EMCG

